

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)  
 Contact Info: [ti.com/support](http://ti.com/support)  
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB  
 Created on: 06/09/2022

Details for "TLV73333PQDRVRQ1"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
TLV73333PQDRVRQ1	NIPDAUAG	Level-1-260C-UNLIM	Ext-Mfg	DRV   6	2x2x0.75	8.5

\*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
<b>Bond Wire</b>							
Precious Metals	Gold	7440-57-5	0.03203	100	1000000	0.378015	3780
Sub-Total			<b>0.03203</b>	<b>100</b>	<b>1000000</b>	<b>0.378015</b>	<b>3780</b>
<b>Die Attach Adhesive</b>							
Other Plastics and Rubber	Other Filler		0.000358	0.500433	5004	0.004225	42
Precious Metals	Silver	7440-22-4	0.058303	81.499343	814993	0.688087	6881
Thermoplastics	Epoxy	85954-11-6	0.012877	18.000224	180002	0.151973	1520
Sub-Total			<b>0.071538</b>	<b>100</b>	<b>1000000</b>	<b>0.844286</b>	<b>8443</b>
<b>Lead Frame</b>							
Copper and Its Alloys	Copper	7440-50-8	3.215645	97.443817	974438	37.950783	379508
Copper and Its Alloys	Iron	7439-89-6	0.07753	2.349395	23494	0.915003	9150
Copper and Its Alloys	Phosphorus	7723-14-0	0.002709	0.082091	821	0.031971	320
Zinc and Its Alloys	Zinc	7440-66-6	0.004115	0.124697	1247	0.048565	486
Sub-Total			<b>3.299999</b>	<b>100</b>	<b>1000000</b>	<b>38.946322</b>	<b>389463</b>
<b>Lead Frame Plating</b>							
Nickel and Its Alloys	Nickel	7440-02-0	0.0973	97.3	973000	1.148327	11483
Precious Metals	Gold	7440-57-5	0.0003	0.3	3000	0.003541	35
Precious Metals	Palladium	7440-05-3	0.0021	2.1	21000	0.024784	248
Precious Metals	Silver	7440-22-4	0.0003	0.3	3000	0.003541	35
Sub-Total			<b>0.1</b>	<b>100</b>	<b>1000000</b>	<b>1.180192</b>	<b>11802</b>
<b>Mold Compound</b>							
Other Inorganic Materials	Fused Silica	60676-86-0	4.303462	89.699991	897000	50.789112	507891
Other Plastics and Rubber	Carbon Black	1333-86-4	0.014393	0.300003	3000	0.169865	1699
Thermoplastics	Epoxy	85954-11-6	0.479762	10.000006	100000	5.662112	56621
Sub-Total			<b>4.797617</b>	<b>100</b>	<b>1000000</b>	<b>56.621089</b>	<b>566211</b>
<b>Semiconductor Device</b>							
Ceramics / Glass	Doped Silicon	7440-21-3	0.172014	100	1000000	2.030095	20301
Sub-Total			<b>0.172014</b>	<b>100</b>	<b>1000000</b>	<b>2.030095</b>	<b>20301</b>
<b>Total</b>			<b>8.473198</b>			<b>100</b>	<b>1000000</b>

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.  
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

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[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to [www.ti.com/ecoinfo](http://www.ti.com/ecoinfo)  
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**RoHS:** Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

**RoHS Exempt:** Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

**Green:** Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=100ppm.